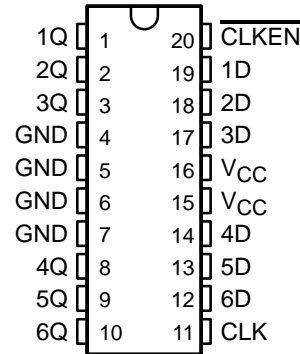


**74AC11378**  
**HEX D-TYPE FLIP-FLOP**  
**WITH CLOCK ENABLE**

SCAS150 – APRIL 1991 – REVISED APRIL 1993

- Contains Six D-Type Flip-Flops
- Clock Enable Latched to Avoid False Clocking
- Applications Include: Buffer/Storage Registers, Shift Registers, Pattern Generators
- Flow-Through Architecture Optimizes PCB Layout
- Center-Pin  $V_{CC}$  and GND Pin Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1- $\mu$ m Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline Packages, and Standard Plastic 300-mil DIPs

**DW OR N PACKAGE**  
(TOP VIEW)



**description**

These circuits are positive-edge-triggered D-type flip-flops with a clock-enable input. Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse if the clock-enable input (CLKEN) is low.

Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock inputs are at either the high or low level, the data (D) input signal has no effect at the output. The circuits are designed to prevent false clocking by transitions at the clock-enable (CLKEN) input.

The 74AC11378 is characterized for operation from – 40°C to 85°C.

**FUNCTION TABLE**  
(each flip-flop)

INPUTS			OUTPUT Q
CLKEN	CLK	D	
H	X	X	$Q_O$
L	↑	H	H
L	↑	L	L
X	L	X	$Q_O$

EPIC is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

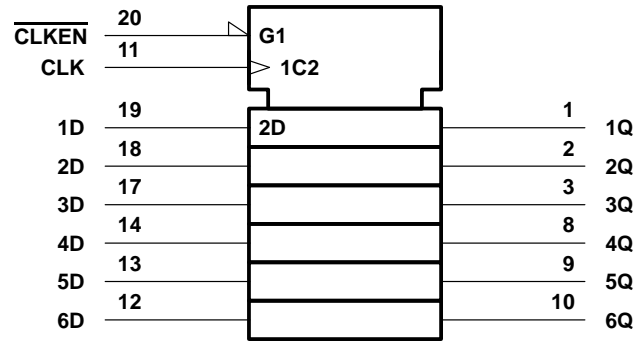


Copyright © 1993, Texas Instruments Incorporated

# 74AC11378 HEX D-TYPE FLIP-FLOP WITH CLOCK ENABLE

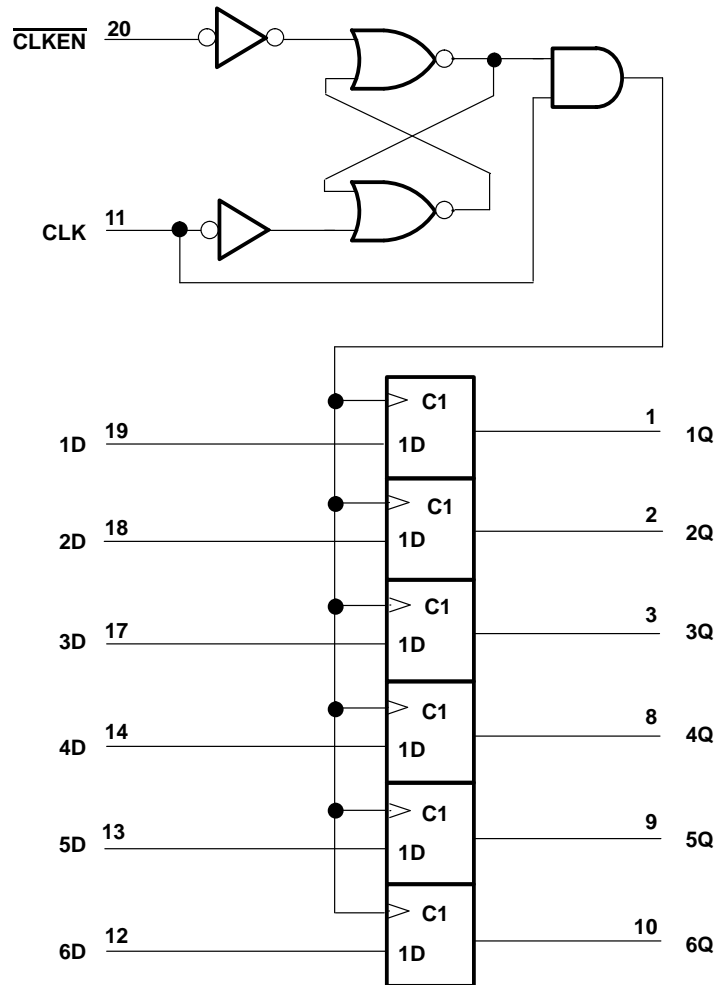
SCAS150 – APRIL 1991 – REVISED APRIL 1993

## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)



**74AC11378**  
**HEX D-TYPE FLIP-FLOP**  
**WITH CLOCK ENABLE**

SCAS150 – APRIL 1991 – REVISED APRIL 1993

**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$ .....	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range, $V_O$ (see Note 1) .....	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) .....	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	±50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	±50 mA
Continuous current through $V_{CC}$ or GND pins .....	±150 mA
Storage temperature range .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

**recommended operating conditions**

		MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage	3	5	5.5	V
$V_{IH}$	High-level input voltage	$V_{CC} = 3$ V	2.1		V
		$V_{CC} = 4.5$ V	3.15		
		$V_{CC} = 5.5$ V	3.85		
$V_{IL}$	Low-level input voltage	$V_{CC} = 3$ V		0.9	V
		$V_{CC} = 4.5$ V		1.35	
		$V_{CC} = 5.5$ V		1.65	
$V_I$	Input voltage	0		$V_{CC}$	V
$V_O$	Output voltage	0		$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 3$ V		–4	mA
		$V_{CC} = 4.5$ V		–24	
		$V_{CC} = 5.5$ V		–24	
$I_{OL}$	Low-level output current	$V_{CC} = 3$ V		12	mA
		$V_{CC} = 4.5$ V		24	
		$V_{CC} = 5.5$ V		24	
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
$T_A$	Operating free-air temperature	–40		85	°C



**74AC11378**  
**HEX D-TYPE FLIP-FLOP**  
**WITH CLOCK ENABLE**

SCAS150 – APRIL 1991 – REVISED APRIL 1993

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	TA = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	3 V	2.9			2.9		V
		4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
	I <sub>OH</sub> = -4 mA	3 V	2.58			2.48		
		4.5 V	3.94			3.8		
		5.5 V	4.94			4.8		
I <sub>OH</sub> = -75 mA†	5.5 V				3.85			
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	3 V				0.1		V
		4.5 V				0.1		
		5.5 V				0.1		
	I <sub>OL</sub> = 12 mA	3 V				0.36		
		4.5 V				0.36		
		5.5 V				0.36		
I <sub>OL</sub> = 24 mA	5.5 V				1.65			
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V				±0.1		μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V				8		μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V	4					pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

**timing requirements over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)**

		TA = 25°C		MIN	MAX	UNIT
		MIN	MAX			
f <sub>clock</sub>	Clock frequency	0	90	0	90	MHz
t <sub>w</sub>	Pulse duration	CLK high or low		5.5		ns
t <sub>su</sub>	Setup time, before CLK↑	Data		8		ns
		CLKEN high or low		6.5		
t <sub>h</sub>	Hold time, after CLK↑	Data		0		ns
		CLKEN high or low		0		

**timing requirements over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)**

		TA = 25°C		MIN	MAX	UNIT
		MIN	MAX			
f <sub>clock</sub>	Clock frequency	0	110	0	110	MHz
t <sub>w</sub>	Pulse duration	CLK high or low		4		ns
t <sub>su</sub>	Setup time, before CLK↑	Data		5		ns
		CLKEN high or low		4.5		
t <sub>h</sub>	Hold time, after CLK↑	Data		0		ns
		CLKEN high or low		0		



**74AC11378**  
**HEX D-TYPE FLIP-FLOP**  
**WITH CLOCK ENABLE**

SCAS150 – APRIL 1991 – REVISED APRIL 1993

**switching characteristics over recommended operating free-air temperature range,  
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$  (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
$f_{\text{max}}$			90	115		90		MHz
$t_{\text{PLH}}$	CLK	Any Q	3	7.6	9.5	3	10.9	ns
$t_{\text{PHL}}$			3.6	9.8	12.8	3.6	14	

**switching characteristics over recommended operating free-air temperature range,  
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
$f_{\text{max}}$			110	140		110		MHz
$t_{\text{PLH}}$	CLK	Any Q	2.4	4.3	7	2.4	7.7	ns
$t_{\text{PHL}}$			3	6.2	8.8	3	9.7	

**operating characteristics,  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$**

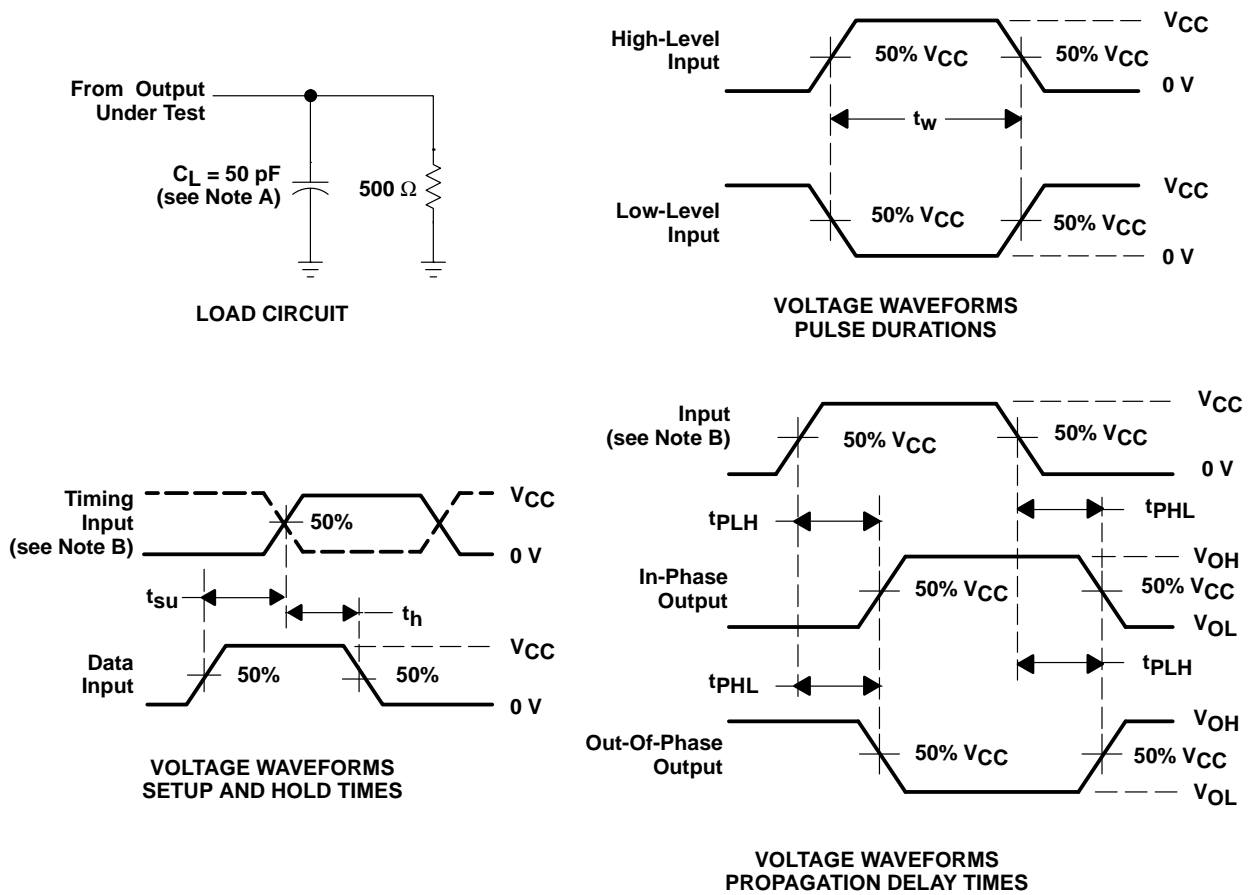
PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{\text{pd}}$ Power dissipation capacitance	$C_L = 50\text{ pF}$ , $f = 1\text{ MHz}$	30	pF



**74AC11378**  
**HEX D-TYPE FLIP-FLOP**  
**WITH CLOCK ENABLE**

SCAS150 – APRIL 1991 – REVISED APRIL 1993

**PARAMETER MEASUREMENT INFORMATION**



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ ,  $t_r = 3$  ns,  $t_f = 3$  ns.  
 C. The outputs are measured one at a time with one input transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

## **IMPORTANT NOTICE**

Texas Instruments (TI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

TI warrants performance of its semiconductor products and related software to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Certain applications using semiconductor products may involve potential risks of death, personal injury, or severe property or environmental damage ("Critical Applications").

**TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS.**

Inclusion of TI products in such applications is understood to be fully at the risk of the customer. Use of TI products in such applications requires the written approval of an appropriate TI officer. Questions concerning potential risk applications should be directed to TI through a local SC sales office.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards should be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor does TI warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.